

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - soldering point (Pin 4)	R_{thJS}	-	-	25	K/W
SMD version, device on PCB:	R_{thJA}				K/W
@ min. footprint		-	-	115	
@ 6 cm ² cooling area ¹⁾		-	-	70	

Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain- source breakdown voltage $V_{GS} = 0\text{ V}$, $I_D = -250\text{ }\mu\text{A}$	$V_{(BR)DSS}$	-60	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D = -160\text{ }\mu\text{A}$	$V_{GS(th)}$	-1	-1.5	-2	
Zero gate voltage drain current $V_{DS} = -60\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 25\text{ }^{\circ}\text{C}$ $V_{DS} = -60\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 125\text{ }^{\circ}\text{C}$	I_{DSS}	- -	-0.1 -10	-1 -100	μA
Gate-source leakage current $V_{GS} = -20\text{ V}$, $V_{DS} = 0\text{ V}$	I_{GSS}	-	-10	-100	nA
Drain-Source on-state resistance $V_{GS} = -4.5\text{ V}$, $I_D = -0.89\text{ A}$	$R_{DS(on)}$	-	0.8	1.4	Ω
Drain-Source on-state resistance $V_{GS} = -10\text{ V}$, $I_D = -1.17\text{ A}$	$R_{DS(on)}$	-	0.5	0.8	Ω

¹⁾Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Transconductance $V_{DS} \leq 2 \cdot I_D \cdot R_{DS(ON)max}$, $I_D = -0.89$ A	g_{fs}	0.7	1.4	-	S
Input capacitance $V_{GS} = 0$ V, $V_{DS} = -25$ V, $f = 1$ MHz	C_{iss}	-	130	160	pF
Output capacitance $V_{GS} = 0$ V, $V_{DS} = -25$ V, $f = 1$ MHz	C_{oss}	-	40	50	
Reverse transfer capacitance $V_{GS} = 0$ V, $V_{DS} = -25$ V, $f = 1$ MHz	C_{rss}	-	17	21	
Turn-on delay time $V_{DD} = -30$ V, $V_{GS} = -4.5$ V, $I_D = -0.89$ A, $R_G = 18$ Ω	$t_{d(ON)}$	-	24	36	ns
Rise time $V_{DD} = -30$ V, $V_{GS} = -4.5$ V, $I_D = -0.89$ A, $R_G = 18$ Ω	t_r	-	9	14	
Turn-off delay time $V_{DD} = -30$ V, $V_{GS} = -4.5$ V, $I_D = -0.89$ A, $R_G = 18$ Ω	$t_{d(OFF)}$	-	32	48	
Fall time $V_{DD} = -30$ V, $V_{GS} = -4.5$ V, $I_D = -0.89$ A, $R_G = 18$ Ω	t_f	-	19	28	

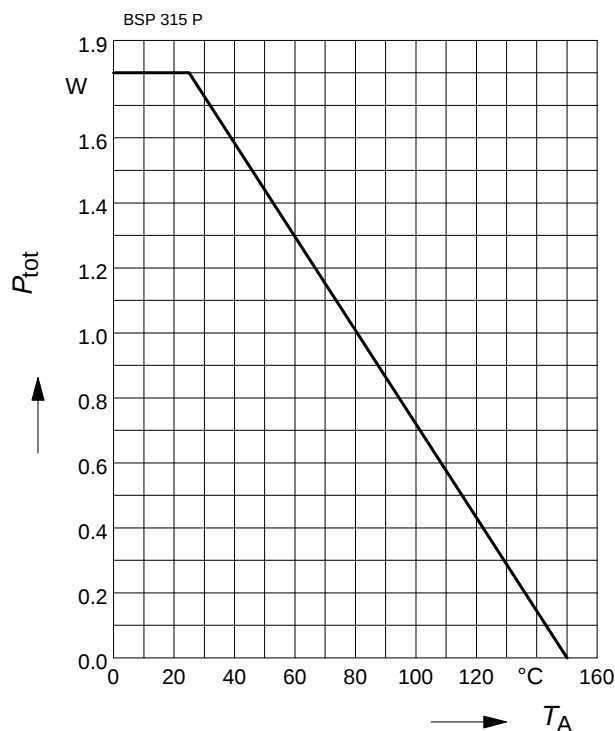
Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Gate to source charge $V_{DD} = -48\text{ V}$, $I_D = -1.17\text{ A}$	Q_{gs}	-	0.7	1.1	nC
Gate to drain charge $V_{DD} = -48\text{ V}$, $I_D = -1.17\text{ A}$	Q_{gd}	-	1.8	2.6	
Gate charge total $V_{DD} = -48\text{ V}$, $I_D = -1.17\text{ A}$, $V_{GS} = 0\text{ to }-10\text{ V}$	Q_g	-	5.2	7.8	
Gate plateau voltage $V_{DD} = -48\text{ V}$, $I_D = -1.17\text{ A}$	$V_{(plateau)}$	-	-3.14	-	V

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse Diode					
Inverse diode continuous forward current $T_A = 25\text{ }^{\circ}\text{C}$	I_S	-	-	-1.17	A
Inverse diode direct current,pulsed $T_A = 25\text{ }^{\circ}\text{C}$	I_{SM}	-	-	-4.68	
Inverse diode forward voltage $V_{GS} = 0\text{ V}$, $I_F = -1.17\text{ A}$	V_{SD}	-	-0.97	-1.3	V
Reverse recovery time $V_R = -30\text{ V}$, $I_F = I_S$, $di_F/dt = 100\text{ A}/\mu\text{s}$	t_{rr}	-	30.5	46	ns
Reverse recovery charge $V_R = -30\text{ V}$, $I_F = I_S$, $di_F/dt = 100\text{ A}/\mu\text{s}$	Q_{rr}	-	36	54	μC

Power Dissipation

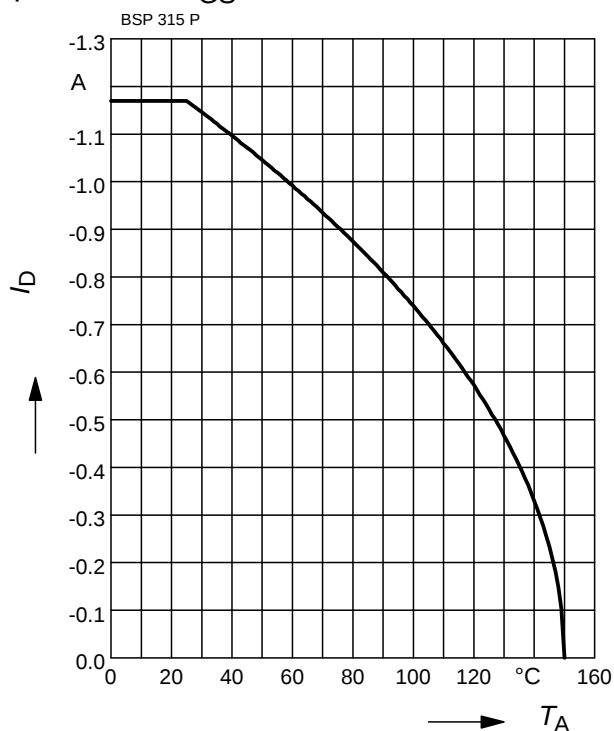
$$P_{\text{tot}} = f(T_A)$$



Drain current

$$I_D = f(T_A)$$

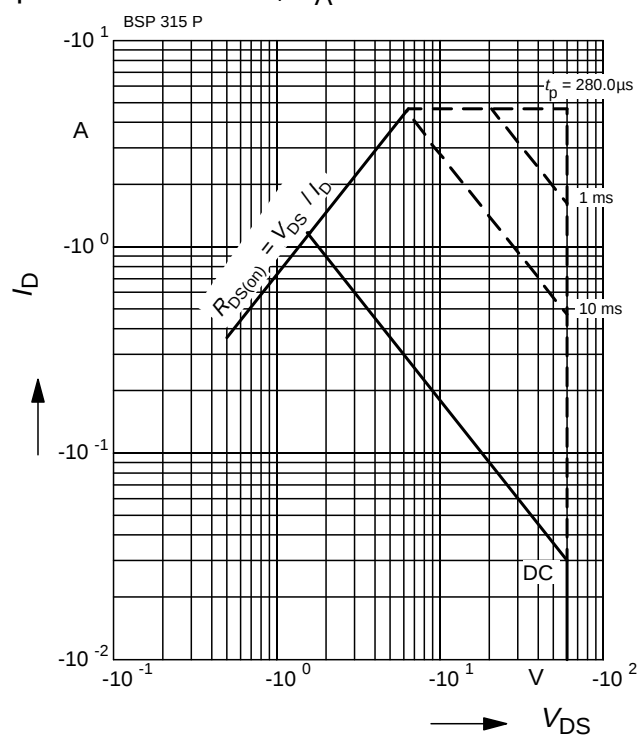
parameter : $V_{GS} \geq -10V$



Safe operating area

$$I_D = f(V_{DS})$$

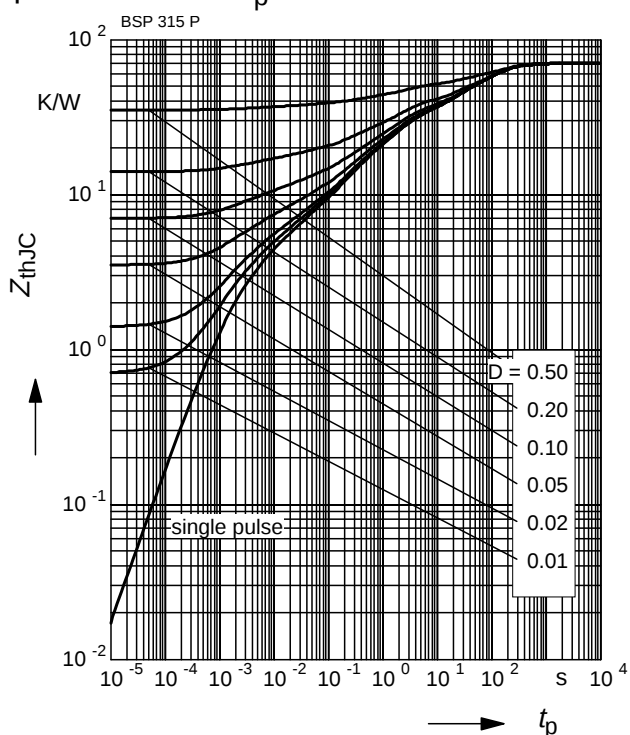
parameter : $D = 0$, $T_A = 25^\circ\text{C}$



Transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

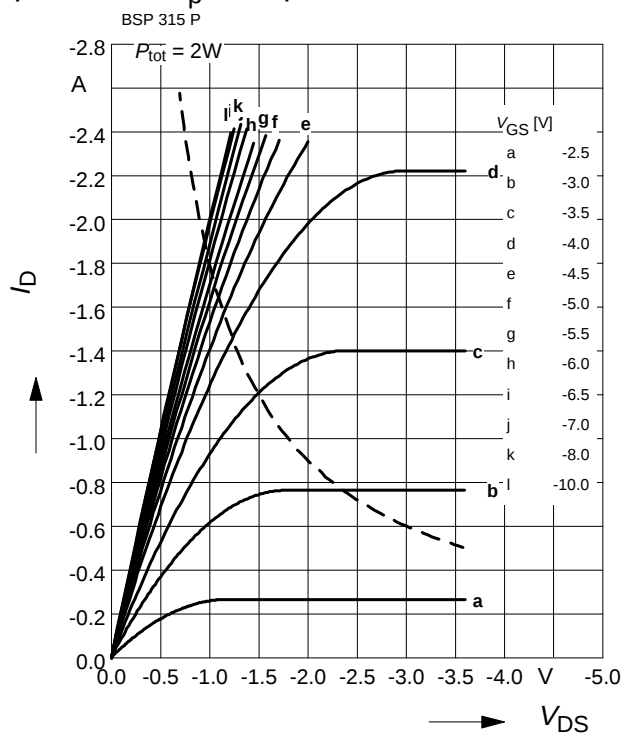
parameter : $D = t_p/T$



Typ. output characteristics

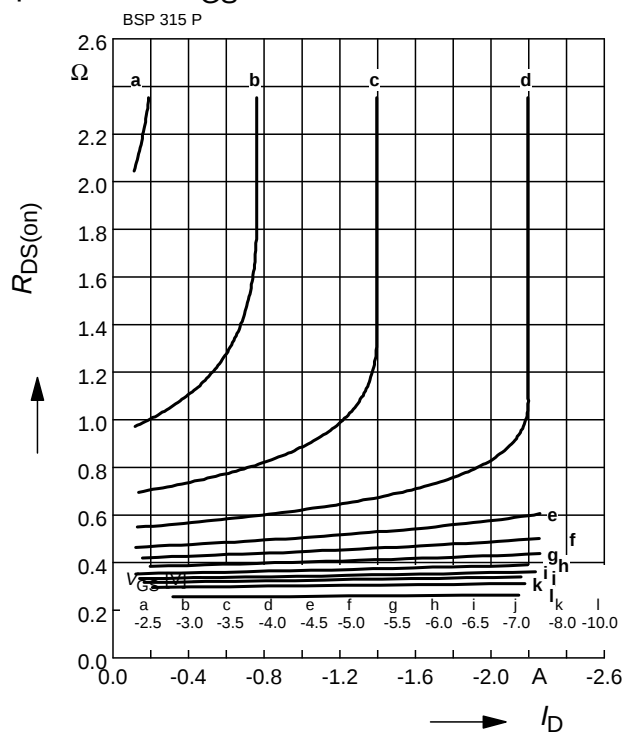
$$I_D = f(V_{DS})$$

parameter: $t_p = 80 \mu s$


Typ. drain-source-on-resistance

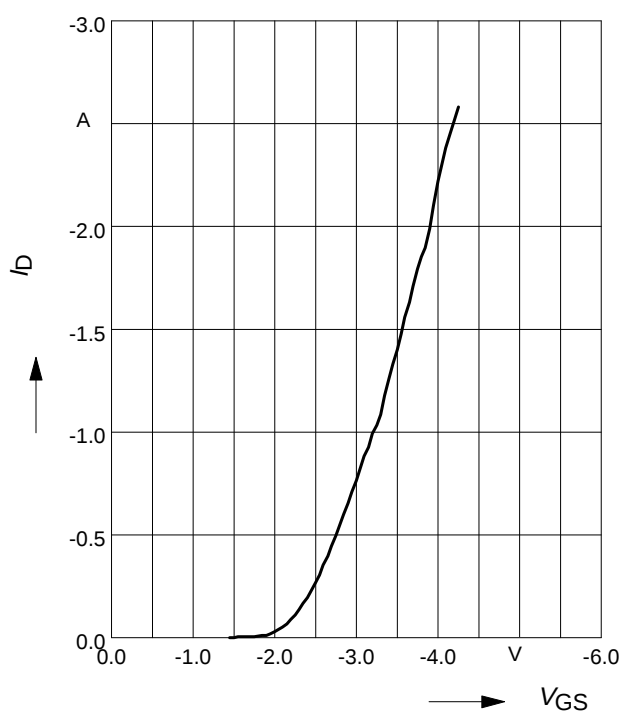
$$R_{DS(on)} = f(I_D)$$

parameter: V_{GS}


Typ. transfer characteristics $I_D = f(V_{GS})$

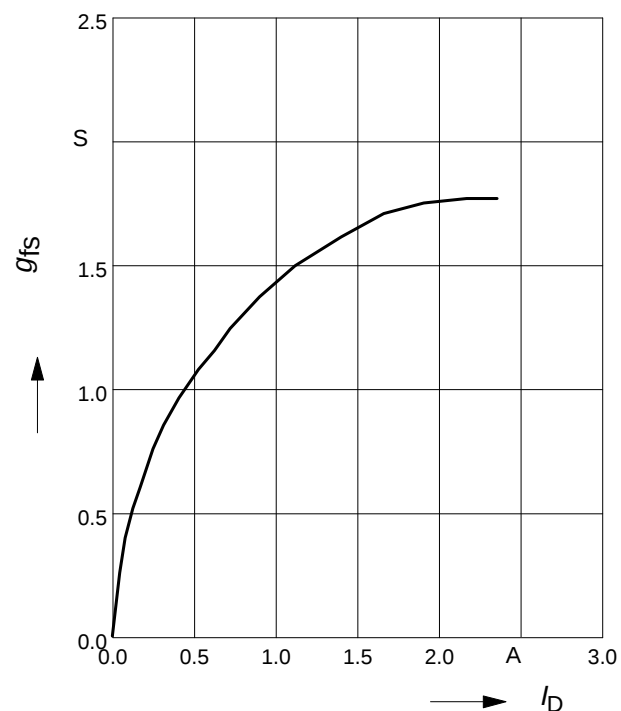
$$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$

parameter: $t_p = 80 \mu s$


Typ. forward transconductance

$$g_{fs} = f(I_D); T_j = 25^\circ C$$

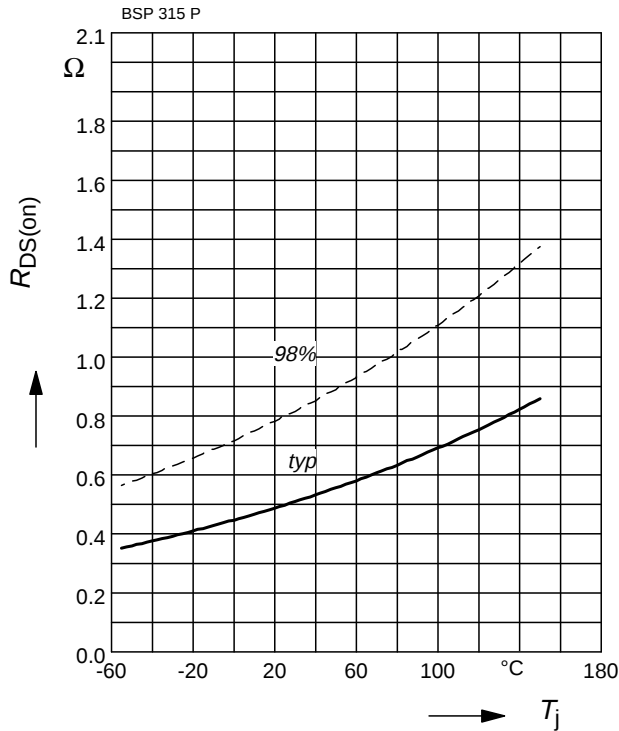
parameter: g_{fs}



Drain-source on-resistance

$$R_{DS(on)} = f(T_j)$$

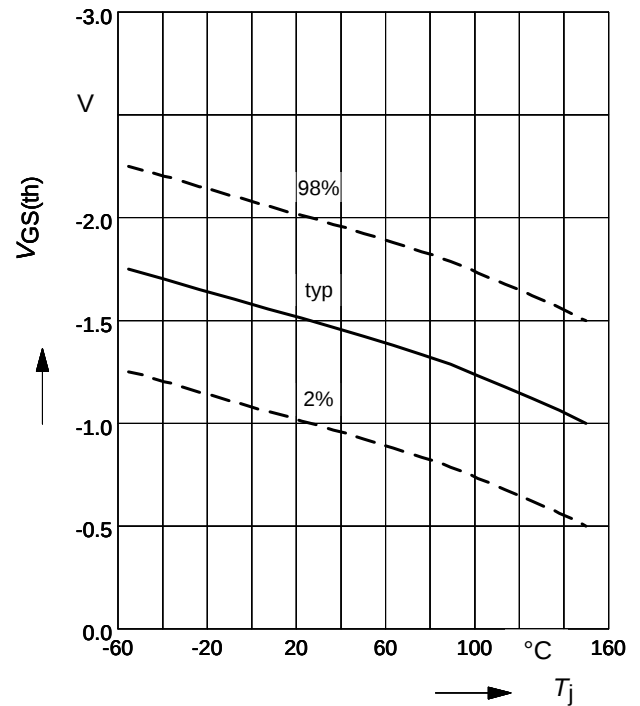
parameter: $I_D = -1.17$ A, $V_{GS} = -10$ V



Gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

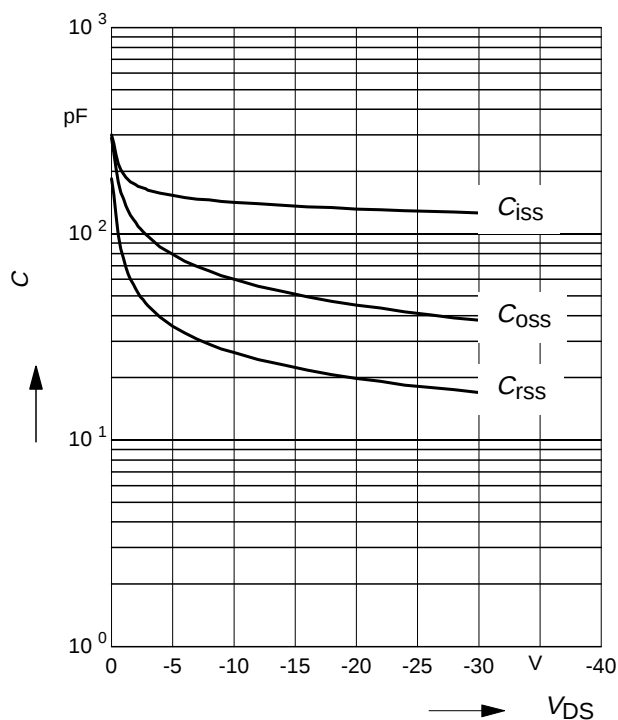
parameter: $V_{GS} = V_{DS}$, $I_D = -160$ μA



Typ. capacitances

$$C = f(V_{DS})$$

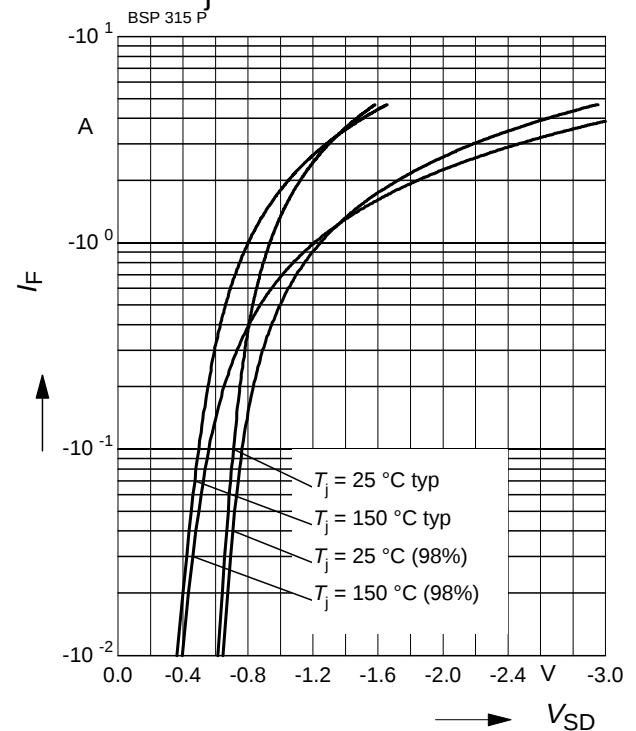
Parameter: $V_{GS} = 0$ V, $f = 1$ MHz



Forward characteristics of reverse diode

$$I_F = f(V_{SD})$$

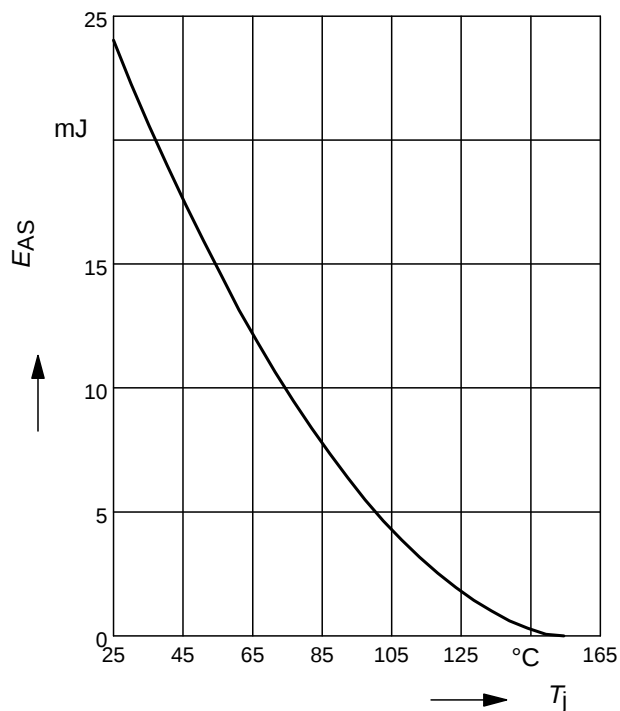
parameter: T_j , $t_p = 80$ μs



Avalanche Energy $E_{AS} = f(T_j)$

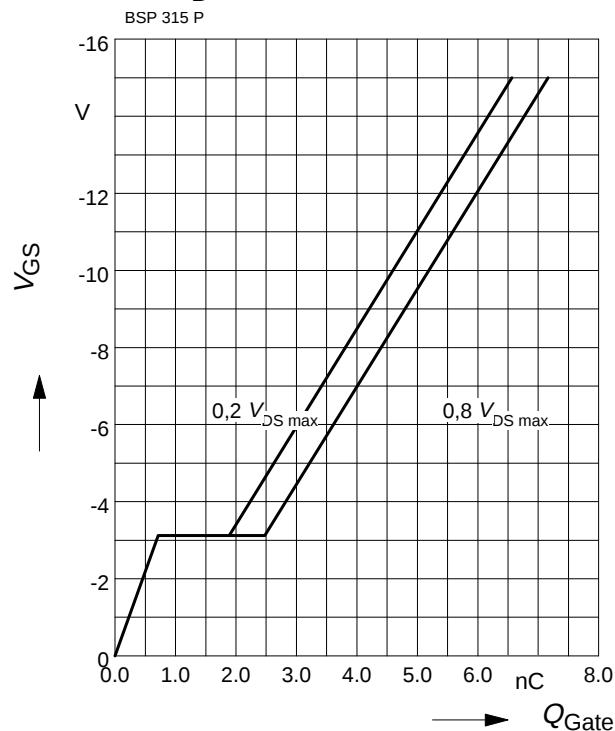
parameter: $I_D = -1.17\text{ A}$, $V_{DD} = -25\text{ V}$

$R_{GS} = 25\ \Omega$

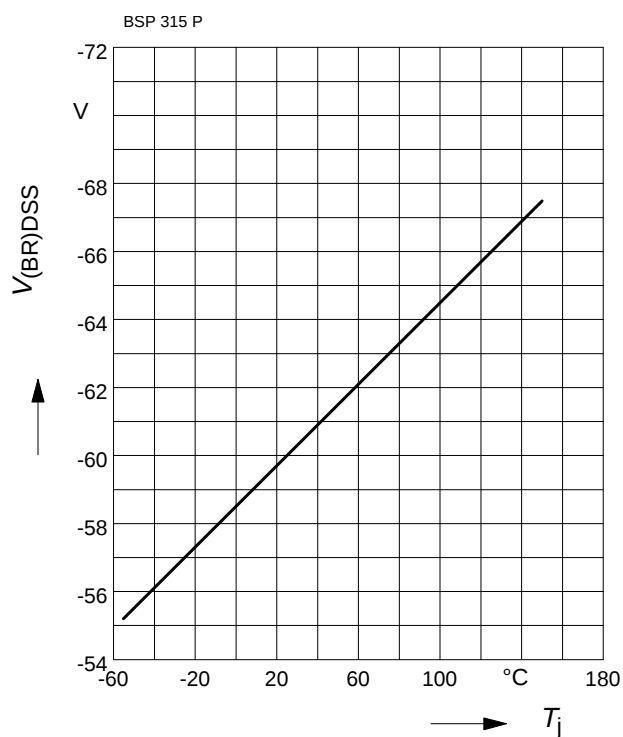

Typ. gate charge

$V_{GS} = f(Q_{Gate})$

parameter: $I_D = -1.17\text{ A}$ pulsed


Drain-source breakdown voltage

$V_{(BR)DSS} = f(T_j)$



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Infineon Technologies AG
81726 Munich, Germany
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